



IPC Southeast Asia High Reliability Conferences 2019

Hanoi, Vietnam - 8 May | Manila, Philippines - 10 May | HCM, Vietnam - 14 August | Bangkok, Thailand - 16 August | Penang, Malaysia - Sep-Oct

Call for Papers and Sponsorship

High Reliability is critical when electronics assemblies are working in harsh environments where there are high temperature difference and vibration. These important one-day events will focus on advanced research results, practical methodologies and standards in the **automotive, aerospace and other electronic fields**—critical information for engineers and managers responsible for reliability.

Present your work and make an impact at this important event that will take participants through the assembly process — from materials to test and inspection — and provide the latest information to increase reliability.

As a speaker, you will be promoted as an industry expert in IPC communications distributed to a global audience and event participants. This is a unique and cost-effective channel for promoting your organization's capabilities and an opportunity to make a contribution to the industry.

Topics of interest include:

- Adhesives and Underfill
- Cable and Wire Harness
- Cleaning and Conformal Coating
- Design for ESD, Manufacturing, Reliability and Test
- Electronics Packaging, Components and RF
- Environmental Compliance/Regulations
- Interconnections on PCB
- Lead-free Assembly
- Materials and Processing
- Solder Alloys
- Yield and Quality Control in Manufacturing

Requirements for Submission

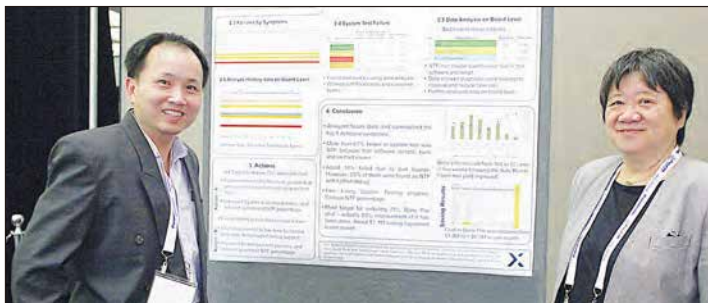
Your submission must be received two months before the event starts:

- An abstract of 200 to 300 words that summarizes recent technical work — case histories, research and discoveries
- Your professional biography
- Complete contact information

Your presentation should be non-commercial in nature and describe significant results from experiments, emphasize new techniques, discuss trends of interest or contain technical and/or appropriate test results. Suggested time for presentations is 45 minutes.

How to Submit

To submit your proposal for a conference presentation, or to learn about conference participation, please contact **Raymond Foo** at RaymondFoo@ipc.org



Sponsorship Information

*Sponsorship fee per event:

Gold Sponsor

US\$1,600 IPC Member/US\$2,000 Nonmember

- Speaking Opportunity
 - One technical conference session to share your solutions, best practices and case studies
- Exhibit Space
- Conference Marketing
 - Logo on all printed materials and agenda on-site
 - Logo on all electronic promotional material
 - Logo on conference website
- List of Conference Attendees

Supporting Sponsor

US\$400 IPC Member / US\$500 Nonmember

- Pre-Conference Marketing
 - Logo on all printed materials and agenda on-site
 - Logo on all electronic promotional material
 - Logo on conference website
- List of Conference Attendees

***20% discount for sponsorship of all events**

Conference Participation

- Lunch and two coffee breaks will be provided to all registered participants
- Complimentary event proceedings and conference kit.
- Opportunity for networking among the leading technology experts.

Contact us for more information:

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